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With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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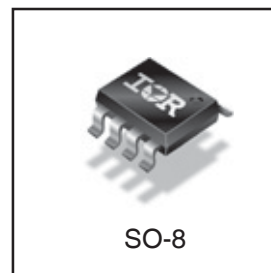
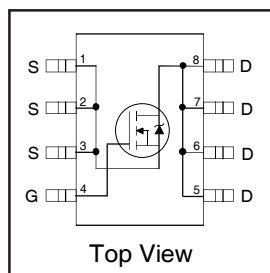
International IR Rectifier

IRF7452QPbF

- Advanced Process Technology
- Ultra Low On-Resistance
- N Channel MOSFET
- Surface Mount
- Available in Tape & Reel
- 150°C Operating Temperature
- Lead-Free

HEXFET® Power MOSFET

V_{DSS}	R_{DS(on) max}	I_D
100V	0.060Ω	4.5A



Description

These HEXFET® Power MOSFET's in SO-8 package utilize the latest processing techniques to achieve extremely low on-resistance per silicon area. Additional features of these HEXFET Power MOSFET's are a 150°C junction operating temperature, fast switching speed and improved repetitive avalanche rating. These benefits combine to make this design an extremely efficient and reliable device for use in a wide variety of applications.

The efficient SO-8 package provides enhanced thermal characteristics making it ideal in a variety of power applications. This surface mount SO-8 can dramatically reduce board space and is also available in Tape & Reel.

Base part number	Orderable part number	Package Type	Standard Pack		EOL Notice	Replacement Part Number
			Form	Quantity		
IRF7452QPbF	IRF7452QTRPbF	SO-8	Tape and Reel	4000	EOL 529	Please search the EOL part number on IR's website for guidance
	IRF7452QPbF	SO-8	Tube	95	EOL 529	

Absolute Maximum Ratings

	Parameter	Max.	Units
I _D @ T _A = 25°C	Continuous Drain Current, V _{GS} @ 10V	4.5	A
I _D @ T _A = 70°C	Continuous Drain Current, V _{GS} @ 10V	3.6	
I _{DM}	Pulsed Drain Current ①	36	
P _D @ T _A = 25°C	Power Dissipation	2.5	W
	Linear Derating Factor	0.02	W/°C
V _{GS}	Gate-to-Source Voltage	± 30	V
dv/dt	Peak Diode Recovery dv/dt ②	3.5	V/ns
T _J	Operating Junction and	-55 to + 150	°C
T _{STG}	Storage Temperature Range		
	Soldering Temperature, for 10 seconds	300 (1.6mm from case)	

Typical SMPS Topologies

- Telecom 48V input DC-DC with Half Bridge Primary or Datacom 28V input with Passive Reset Forward Converter Primary

Notes ① through ⑥ are on page 8

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Static @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
V _{(BR)DSS}	Drain-to-Source Breakdown Voltage	100	—	—	V	V _{GS} = 0V, I _D = 250μA
ΔV _{(BR)DSS} /ΔT _J	Breakdown Voltage Temp. Coefficient	—	0.11	—	V/°C	Reference to 25°C, I _D = 1mA ⑥
R _{DS(on)}	Static Drain-to-Source On-Resistance	—	—	0.060	Ω	V _{GS} = 10V, I _D = 2.7A ④
V _{GS(th)}	Gate Threshold Voltage	3.0	—	5.5	V	V _{DS} = V _{GS} , I _D = 250μA
I _{DSS}	Drain-to-Source Leakage Current	—	—	25	μA	V _{DS} = 100V, V _{GS} = 0V
		—	—	250		V _{DS} = 80V, V _{GS} = 0V, T _J = 150°C
I _{GSS}	Gate-to-Source Forward Leakage	—	—	100	nA	V _{GS} = 24V
	Gate-to-Source Reverse Leakage	—	—	-100		V _{GS} = -24V

Dynamic @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
g _{fs}	Forward Transconductance	3.4	—	—	S	V _{DS} = 50V, I _D = 2.7A
Q _g	Total Gate Charge	—	33	50	nC	I _D = 2.7A
Q _{gs}	Gate-to-Source Charge	—	7.3	11		V _{DS} = 80V
Q _{gd}	Gate-to-Drain ("Miller") Charge	—	16	24		V _{GS} = 10V, ④
t _{d(on)}	Turn-On Delay Time	—	9.5	—	ns	V _{DD} = 50V
t _r	Rise Time	—	11	—		I _D = 2.7A
t _{d(off)}	Turn-Off Delay Time	—	16	—		R _G = 6.0Ω
t _f	Fall Time	—	13	—		V _{GS} = 10V ④
C _{iss}	Input Capacitance	—	930	—	pF	V _{GS} = 0V
C _{oss}	Output Capacitance	—	300	—		V _{DS} = 25V
C _{rss}	Reverse Transfer Capacitance	—	84	—		f = 1.0MHz
C _{oss}	Output Capacitance	—	1370	—		V _{GS} = 0V, V _{DS} = 1.0V, f = 1.0MHz
C _{oss}	Output Capacitance	—	170	—		V _{GS} = 0V, V _{DS} = 80V, f = 1.0MHz
C _{oss eff.}	Effective Output Capacitance	—	280	—		V _{GS} = 0V, V _{DS} = 0V to 80V ⑤

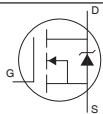
Avalanche Characteristics

	Parameter	Typ.	Max.	Units
E _{AS}	Single Pulse Avalanche Energy②	—	200	mJ
I _{AR}	Avalanche Current①	—	4.5	A
E _{AR}	Repetitive Avalanche Energy①	—	0.25	mJ

Thermal Resistance

	Parameter	Typ.	Max.	Units
R _{θJA}	Maximum Junction-to-Ambient⑥	—	50	°C/W

Diode Characteristics

	Parameter	Min.	Typ.	Max.	Units	Conditions
I _S	Continuous Source Current (Body Diode)	—	—	2.3	A	MOSFET symbol showing the integral reverse p-n junction diode. 
I _{SM}	Pulsed Source Current (Body Diode) ①	—	—	36		
V _{SD}	Diode Forward Voltage	—	—	1.3	V	T _J = 25°C, I _S = 2.7A, V _{GS} = 0V ④
t _{rr}	Reverse Recovery Time	—	77	120	ns	T _J = 25°C, I _F = 2.7A
Q _{rr}	Reverse Recovery Charge	—	270	410	nC	di/dt = 100A/μs ④

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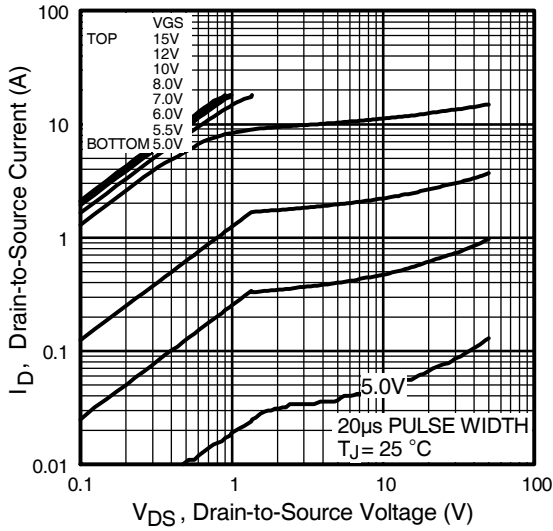


Fig 1. Typical Output Characteristics

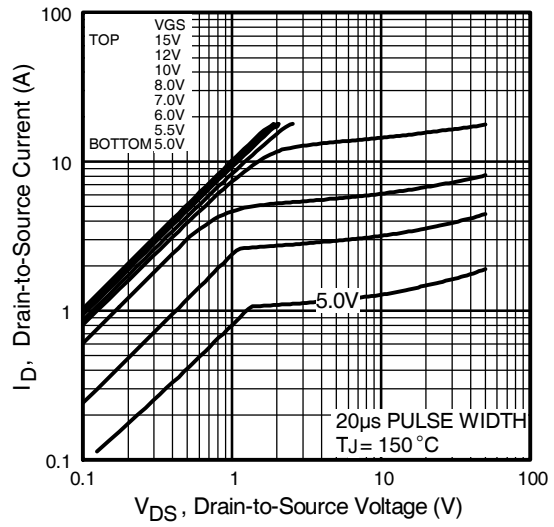


Fig 2. Typical Output Characteristics

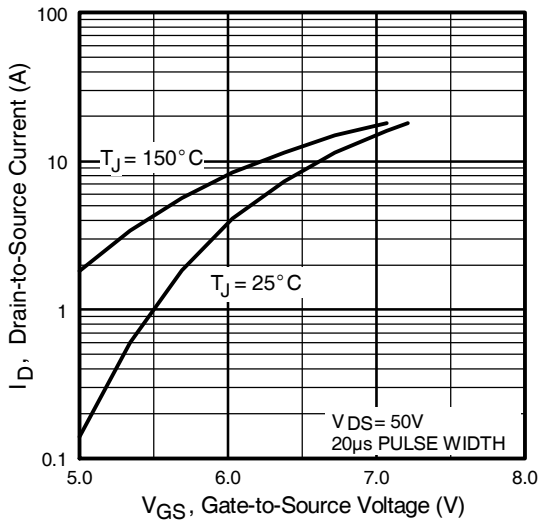


Fig 3. Typical Transfer Characteristics

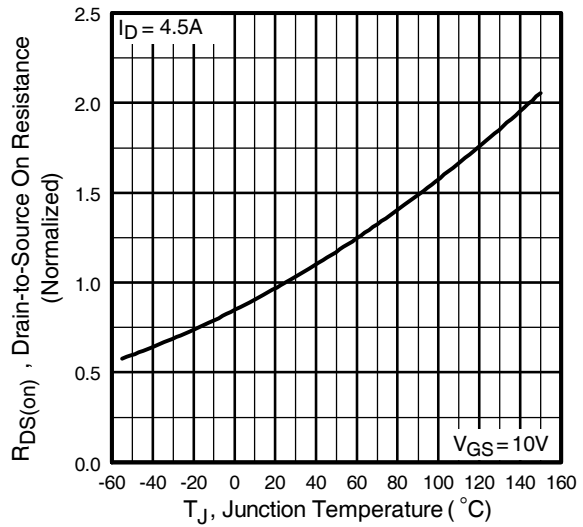


Fig 4. Normalized On-Resistance Vs. Temperature

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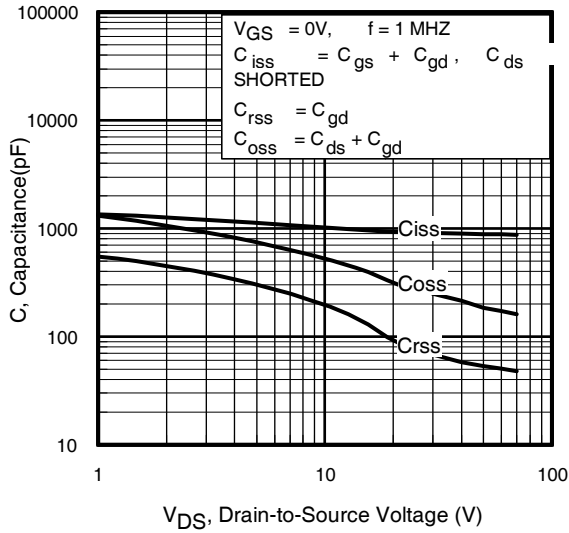


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

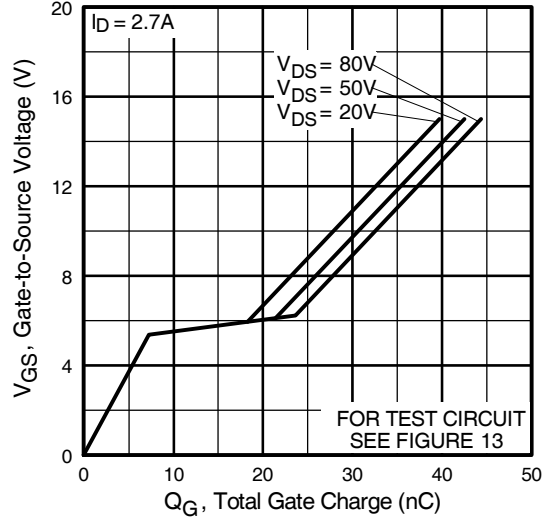


Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage

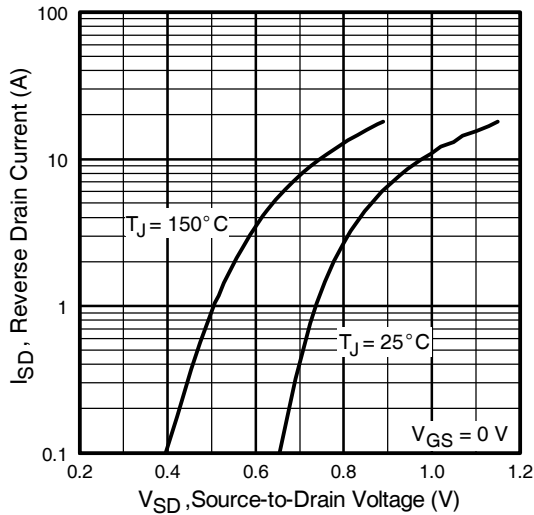


Fig 7. Typical Source-Drain Diode Forward Voltage

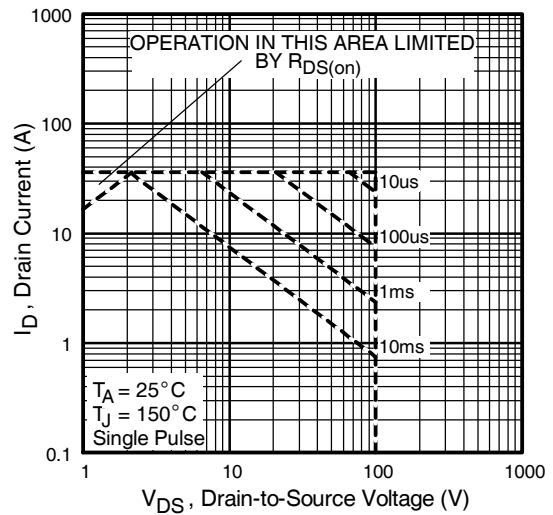


Fig 8. Maximum Safe Operating Area

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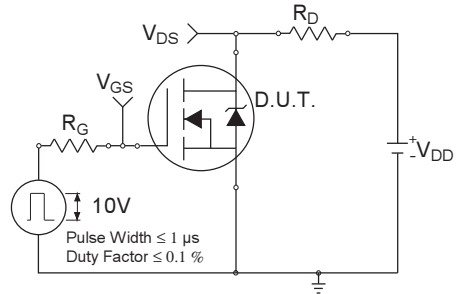
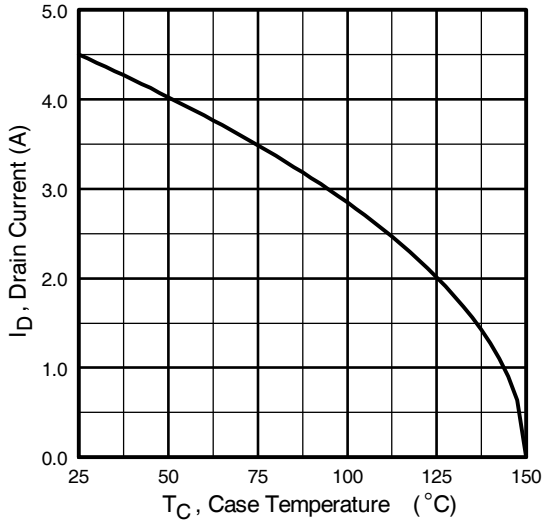


Fig 10a. Switching Time Test Circuit

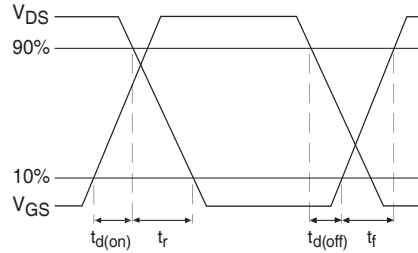


Fig 10b. Switching Time Waveforms

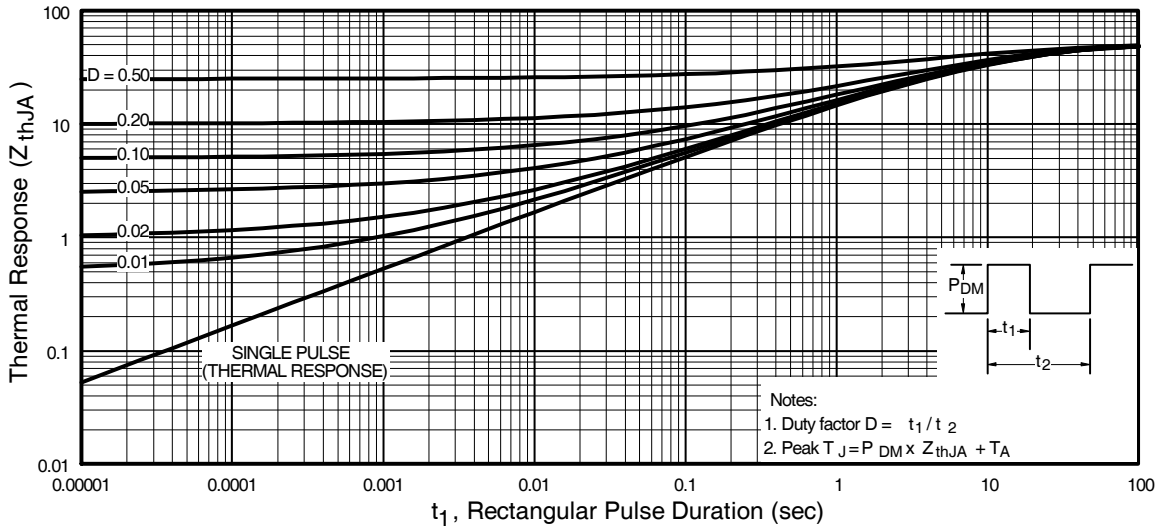


Fig 10. Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

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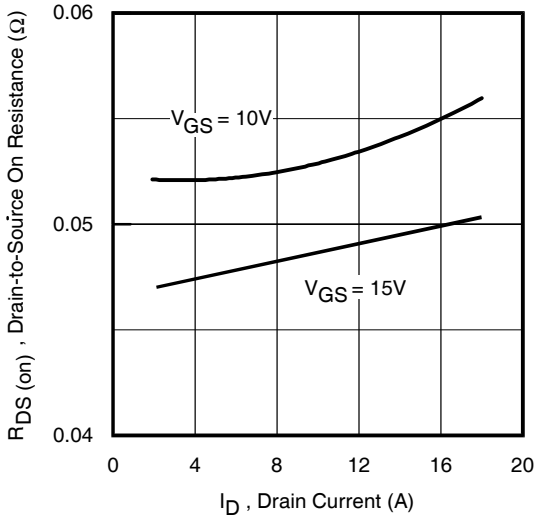


Fig 12. On-Resistance Vs. Drain Current

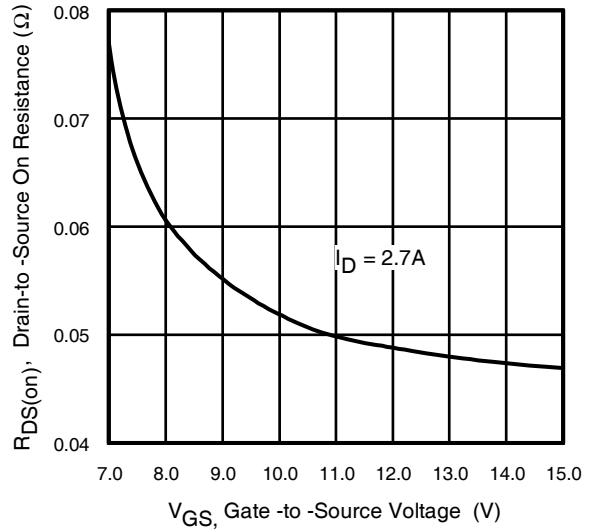


Fig 13. On-Resistance Vs. Gate Voltage

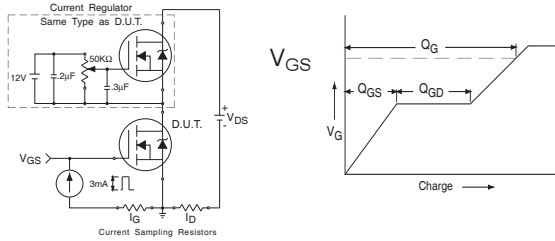


Fig 13a&b. Basic Gate Charge Test Circuit and Waveform

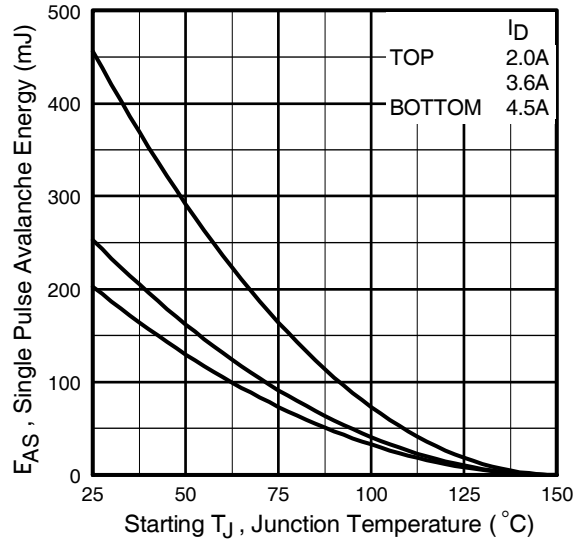


Fig 14c. Maximum Avalanche Energy Vs. Drain Current

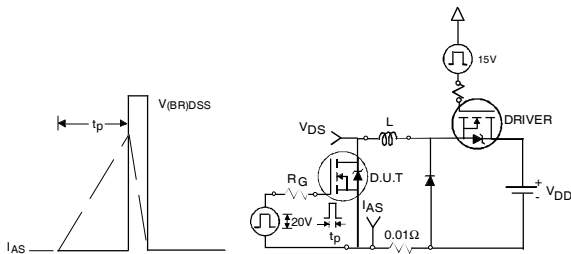


Fig 14a&b. Unclamped Inductive Test circuit and Waveforms

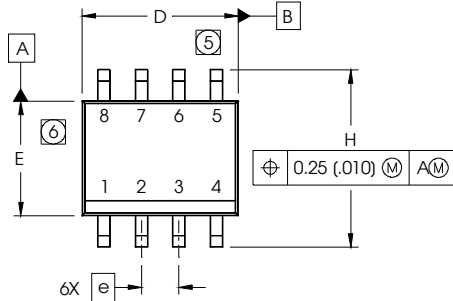
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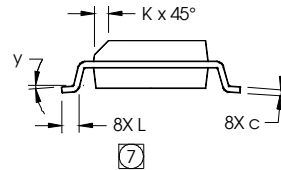
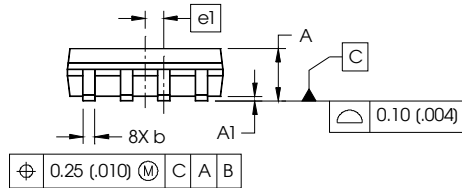
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SO-8 Package Details

Dimensions are shown in millimeters (inches)



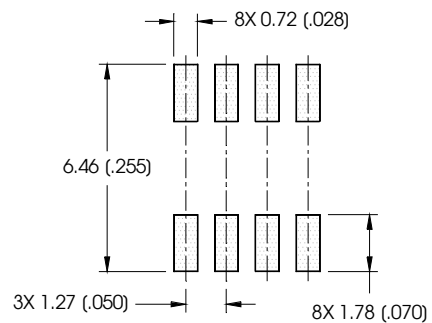
DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.0532	.0688	1.35	1.75
A1	.0040	.0098	0.10	0.25
b	.013	.020	0.33	0.51
c	.0075	.0098	0.19	0.25
D	.189	.1968	4.80	5.00
E	.1497	.1574	3.80	4.00
e	.050 BASIC		1.27 BASIC	
e1	.025 BASIC		0.635 BASIC	
H	.2284	.2440	5.80	6.20
K	.0099	.0196	0.25	0.50
L	.016	.050	0.40	1.27
y	0°	8°	0°	8°



NOTES:

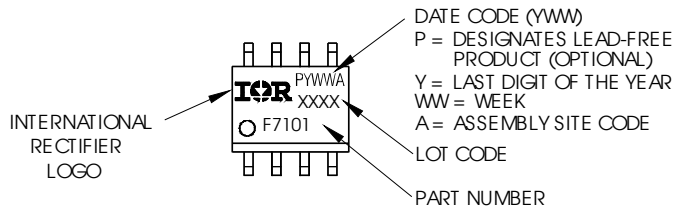
1. DIMENSIONING & TOLERANCING PER ASME Y14.5M-1994.
2. CONTROLLING DIMENSION: MILLIMETER
3. DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).
4. OUTLINE CONFORMS TO JEDEC OUTLINE MS-012AA.
5. DIMENSION DOES NOT INCLUDE MOLD PROTRUSIONS. MOLD PROTRUSIONS NOT TO EXCEED 0.15 (.006).
6. DIMENSION DOES NOT INCLUDE MOLD PROTRUSIONS. MOLD PROTRUSIONS NOT TO EXCEED 0.25 (.010).
7. DIMENSION IS THE LENGTH OF LEAD FOR SOLDERING TO A SUBSTRATE.

FOOTPRINT



SO-8 Part Marking

EXAMPLE: THIS IS AN IRF7101 (MOSFET)



Notes:

1. For an Automotive Qualified version of this part please see: <http://www.irf.com/product-info/automotive/>
2. For the most current drawing please refer to IR website at <http://www.irf.com/package/>

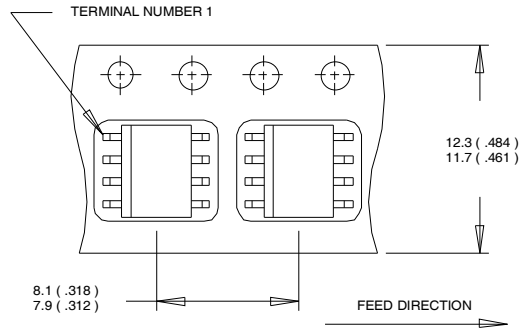
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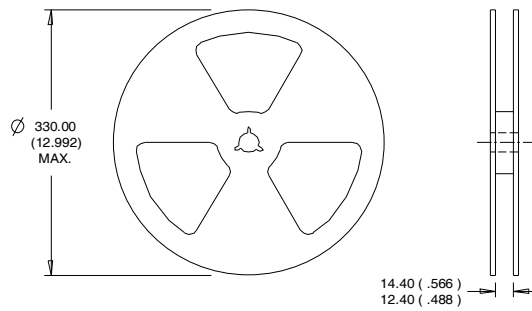
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SO-8 Tape and Reel

Dimensions are shown in millimeters (inches)



- NOTES:
1. CONTROLLING DIMENSION : MILLIMETER.
 2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS(INCHES).
 3. OUTLINE CONFORMS TO EIA-481 & EIA-541.



- NOTES :
1. CONTROLLING DIMENSION : MILLIMETER.
 2. OUTLINE CONFORMS TO EIA-481 & EIA-541.

For the most current drawing please refer to IR website at <http://www.irf.com/package/>

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Qualification Information†

Qualification level	Industrial †	
	(per JEDEC JESD47F†† guidelines)	
Moisture Sensitivity Level	SO-8	MSL1 (per JEDEC J-STD-020D††)
RoHS Compliant	Yes	

† Qualification standards can be found at International Rectifier's web site
<http://www.irf.com/product-info/reliability>

†† Applicable version of JEDEC standard at the time of product release.

Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature.
- ② Starting $T_J = 25^{\circ}\text{C}$, $L = 20\text{mH}$, $R_G = 25\Omega$, $I_{AS} = 4.5\text{A}$.
- ③ Pulse width $\leq 400\mu\text{s}$; duty cycle $\leq 2\%$.
- ④ When mounted on 1 inch square copper board, $t < 10\text{ sec}$

Revision History

Date	Comments
12/19/2014	• Added ordering information to reflect the End-Of-life